	Type	L #	Hits	Search Text	DBs
1	BRS	L1	946	257/783.ccls.	US-PGPUB; USPAT; USOCR
2	BRS	L2	1999	257/787.ccls.	US-PGPUB; USPAT; USOCR
3	BRS	L3	511	257/788.ccls.	US-PGPUB; USPAT; USOCR
4	BRS	L4	158	257/783.ccls.	EPO; JPO; DERWENT; IBM_TDB
5	BRS	L5	1790	257/787.ccls.	EPO; JPO; DERWENT; IBM_TDB
6	BRS	L6	398	257/788.ccls.	EPO; JPO; DERWENT; IBM_TDB
7	BRS	L7	0	((chip or die) and (adheisive or attach or resin or underfill or encapsulat$3) and (peel$3 adj stress) and (modulus or elasticity)).clm.	US-PGPUB
8	BRS	L8	0	((chip or die) and (adhesive or attach or resin or underfill or encapsulat$3) and (peel$3 adj stress) and (modulus or elasticity)).clm.	US-PGPUB

	Type	L #	Hits	Search Text	DBs
9	BRS	L9	7	((chip or die) and (adhesive or attach or resin or underfill or encapsulat$3) and (coefficient or expansion) and (modulus or elasticity) and reflow).clm.	US-PGPUB
10	BRS	L11	18	257/E23.136.ccls.	US-PGPUB; USPAT; USOCR
11	BRS	L10	9	257/E23.116.ccls.	US-PGPUB; USPAT; USOCR